

Product / Process Change Notice

No.: Z200-PCN-AM201612-01-A

Change Title: To add Winstek as an additional assembly site for WLCSP package. Change Classification:

✓ Major

✓ Minor Change item : ☐ Design ☐ Raw Material ☐ Wafer FAB ☐ Assembly ☐ Packing ☐ Testing ☐ Others Affected Product(s): Please refer to Table 1 in details. Description of Change(s) To add new assembly site Winstek Semiconductor Technology Co., Ltd. (Address: No.176-5, 6 Ling, Hua-Lung Chun, Chiung-Lin, Hsin-Chu Hsien, Taiwan, R.O.C. 307.), as an additional assembly site of WLCSP package. Reason for Change(s): To increase the assembly capacity of WLCSP package and meet customers delivery requirement. Impact of Change(s): (positive & negative) Form: No Change Fit: No Change Function: No Concern (Please refer to attachment I) Reliability: No Concern (Please refer to attachment I) Hazardous Substances: No Concern (Please refer to attachment II) Qualification Plan/ Results: (1) Winstek is one company with TS 16949 and ISO 9001 certification.(Please refer to attachment III) (2) Based on Winbond standard package qualification result, the new production line meets our criteria. (please refer to Attachment I) Implementation Plan: ■ Date Code: onward ☐ Lot No: onward ✓ Proposed first ship date: 06/09/2017 Originator: (QA) Approval: (QA Approval: (QRA 4H Char Hyhuang Dept. Manager) Director) Name: Betty Huang TEL:886-3-5678168 (ext.86549) FAX: 886-3-5796124 Contact for Questions Address: #539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan & Concerns E-mail: Hyhuang8@winbond.com

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Date: 12/09/2016



Customer Comments:

Note: Please sign this notice, and return to Winbond contact within **30** days. If no response is received within **30** days, this Change Request will be assumed to meet your approval.

■ Approval	■ Disapproval	□ Conditional Approval :
Comment:		
Date:		
Dept. name:		
Person in charge:		



Table 1. The affected part no are list below.

W25Q16FWBYIG	W25Q80BWBYIG	W25Q16DWYM07	W25Q16DVBYIG	W25Q64FWBYIC
W25Q80BWBJIC	W25Q80BWYS01	W25Q16DWYS02	W25Q80DLBYIG	W25Q64FWBYIF
W25Q80BWBJIG	W25Q80BWYS02	W25Q16DWYS04	W25Q80DVBYIG	W25Q64FWBYIG
W25Q80BWBKIC	W25Q80BWYS03	W25Q16DWYS06	W25Q10EWBYIG	W25Q64FWBYIQ
W25Q80BWBYAA	W25Q32FWBYIQ	W25Q16DWYS09	W25Q20EWBYIG	W25Q32FWBYAA
W25Q80BWBYBB	W25Q16DWBYIG	W25Q16DWYS10	W25Q40EWBYIG	W25Q32FWBYIC
W25Q80BWBYIB	W25Q16DWBYIL	W25Q16DWYS11	W25Q64FVBYIF	W25Q32FWBYIG
W25Q80BWBYIC	W25Q16DWYM03	W25Q80DWBYIG	W25Q64FVBYIQ	

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